

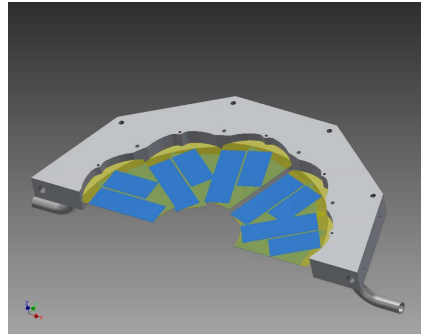
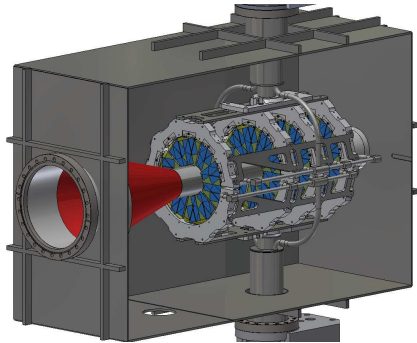
Cables and boards for the Luminosity Detector

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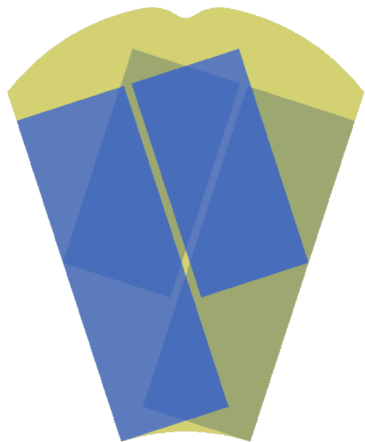
December 10th, 2013



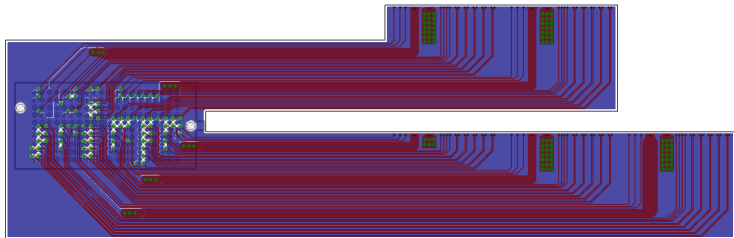


- Flex cables from the sensors to a PCB on the half ring
- PCBs with μ C, LVDS repeater and linear regulators
- Rigid flex cables from the PCB to the feedthroughs

Sensor modules



sensor	readout	
	LVDS	□ □
	CLK	□ □ □ □
	LV	□ □ □ □
	HV	□ □ □ □
	SPI	□ □ □ □ □ □ □ □
	Reset	□ □
	Testpuls	□ □
		□ □
sensor	readout	
	LVDS	□ □
	CLK	□ □ □ □
	LV	□ □ □ □
	HV	□ □ □ □
	SPI	□ □ □ □ □ □ □ □
	Reset	□ □
	Testpuls	□ □
		□ □
sensor	readout	
	LVDS	□ □
	CLK	□ □ □ □
	LV	□ □ □ □
	HV	□ □ □ □
	SPI	□ □ □ □ □ □ □ □
	Reset	□ □
	Testpuls	□ □
		□ □



- Characteristics:

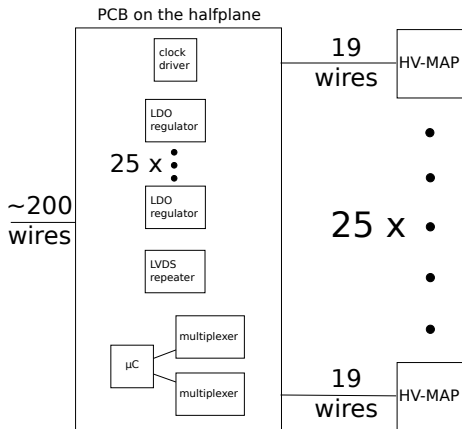
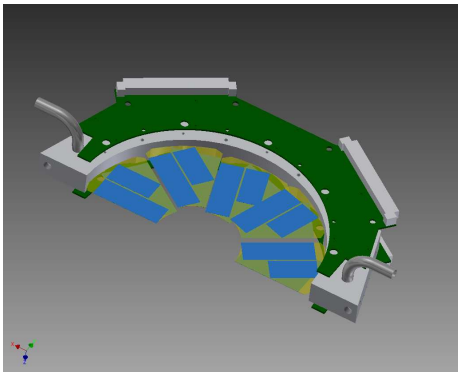
- Trace material: aluminum
- Trace width:
 - Differential (Edge-Coupled Microstrip): $100\text{ }\mu\text{m}$
 - LV: $1400\text{ }\mu\text{m}$
- Trace spacing: $> 100\text{ }\mu\text{m}$
- Trace thickness: $15\text{ }\mu\text{m}$
- Dimensions: $40\text{ mm} \times 110\text{ mm}$
- Cover: Parylene: $5\text{ }\mu\text{m}$

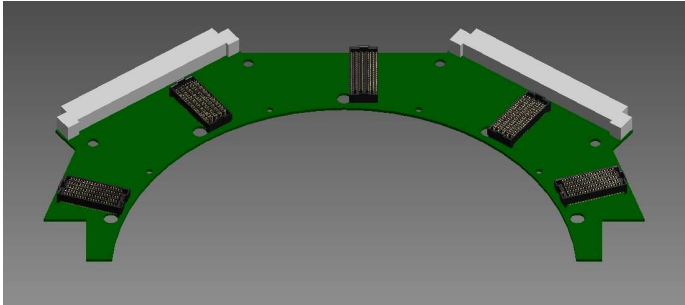
- Advantage of aluminum:

- Short radiation length

- Disadvantage of aluminum:

- High electrical resistance
 - voltage drop
 - high power dissipation



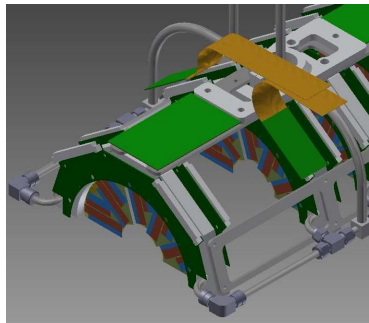


- ICs are placed on the bottom side of the PCB
- Power dissipation of the ICs about 25 W
→ thermal contact between ICs and halfplane necessary
- Connectors (Samtec SEAF and QMS) are placed on the top side of the PCB

Rigid flex cable

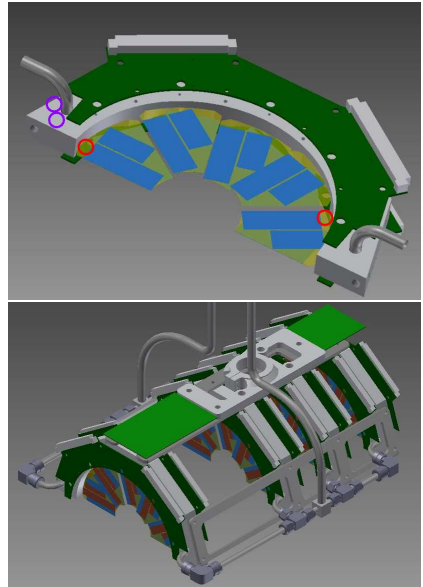


- Dimensions: 83 mm \times 570 mm
- Flex area: $\sim 500 \mu\text{m}$ thick
- Flex area (3 layers):
 - Signal, clock, reset, testpulse
→ 40 differential pairs
(Edge-Coupled Stripline, $Z_{\text{diff}} = 100 \Omega$)
 - HV (26 wires)
 - JTAG (5 wires)
- Rigid area (6 layers):
 - LV
 - CAN bus

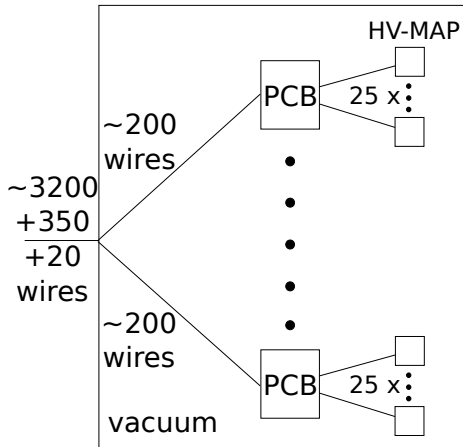
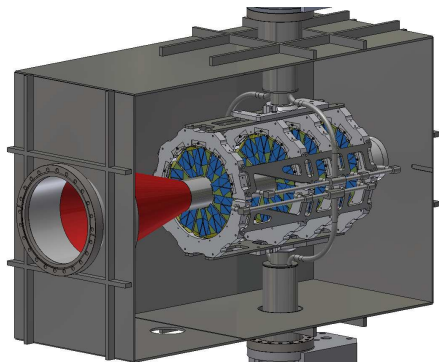


Temperature sensors

- Temperature measurement inside of the detector necessary
 - 88 temperature sensors (PT100) foreseen:
 - 40 temperature sensors (on the diamonds) for monitoring
 - 48 temperature sensors (on the halfplanes and PCB) for overheating protection
- 352 wires
- Maybe NTC Thermistors on the HV-MAPS
 - Patch panel to combine single wires to a FPC

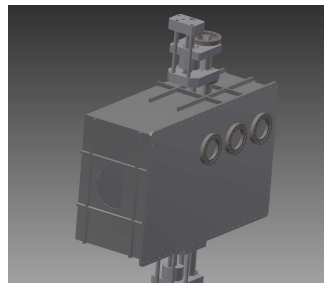
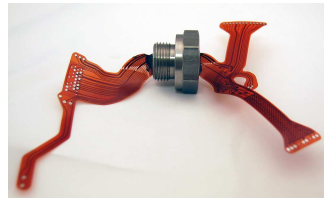


Feedthroughs



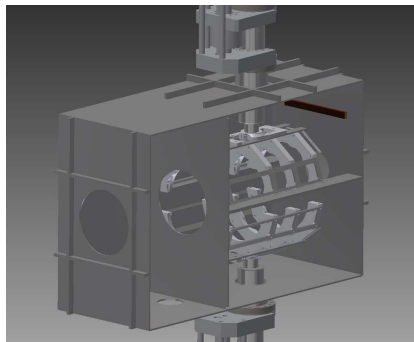
Feedthroughs

- Feedthroughs necessary for about 3600 wires
- Flex cables glued in a flange for
 - Signal
 - Clock
 - JTAG
 - Reset
 - Testpulse
 - HV
- less space necessary than connectors
- FPC of the temperature sensors use the same flange
- Use of high current feedthroughs for the LV
- Seperate feedthrough for CAN bus



Low Voltage

- HV-MAPS need 1.8 V (< 1.6 A)
- Voltage drop on flex cable up to 0.2 V
→ LDO regulator with sense pin necessary
- Use of ADP1740
 - Regulation: < 300 mV
 - $I_{Out} < 2$ A
 - Dimensions: 4 mm \times 4 mm
- Power supply: Wiener PL506 with MEH-02/07
 - Up to 115 A per channel
 - Master-Slave mode for paralleling of channels
 - Noise and ripple (datasheet): < 10 mV
- Use of a current bar in the detector to split the LV to the PCBs



- Cables from the sensors to the PCB have to be very thin
→ Use of flex cables (thk $\sim 70 \mu\text{m}$)
- Estimated voltage drop for the LV up to 0.2 V
→ Use of LDO regulator with sense pin
- ~ 3600 feedthroughs necessary
→ Use of flex cables glued in feedthroughs

Work in progress

- Test of the LVDS repeater and clock distributor
- Test of rigid flex cables
- Radiation tests